

REMARKS

This communication is in response to the Office Action mailed on October 26, 2006. In the Office Action, claims 1-21 and 28-33 were pending. Claims 1-21 were indicated as allowed and claims 28, 29, 31 and 32 were rejected. Additionally, claims 30 and 33 were objected to as being dependent upon a rejected base claim but were indicated as being allowable if rewritten in independent form. With this Amendment, claim 28 has been amended. All remaining claims are unchanged. In view of the following, reconsideration and allowance are requested.

On page 2, claims 28, 29, 31, and 32 were rejected under 35 U.S.C. § 102(b) as being anticipated by Katsumata (U.S. Patent Pub. No. 2001/0030836).

Independent claim 28, as amended, recites "a suspension", "a conductive element positioned on the suspension", "a heating element positioned on the suspension", and "an insulating component positioned between the conductive element and the heating element such that the conductive element and the heating element are electrically isolated."

Katsumata relates to a head suspension assembly having a head IC mounted on a relay and positioned near a magnetic head. Heat dissipation layers are positioned proximate the head IC to encourage heat radiation away from the magnetic head. The Office Action cites "head IC 50" as teaching the heating element of claim 28. Further, "copper foil 82" and "under filler 85" are cited as teaching the conductive element and insulating component of claim 28, respectively. As can be seen in FIGS. 8-10 of Katsumata, the head IC 50 is electrically connected to the copper foil layer 82 by soldering points 81 (see also, para. [0079]). Further, in paragraph [0078], Katsumata describes that the trace 28 comprises "a relay FPC 52 includ[ing] copper foil 82 forming conductive lines 54 and 56." The conductive lines 54 and 56 are

connected to the head IC 50 (see para. [0060]). In particular, a first wiring pattern connects the head IC to the magnetic head while a second wiring pattern in trace 28 connects the head IC to the electrode pad section 53 (para. [0060]).


As can be seen from the cited sections of Katsumata discussed above, the head IC is electrically connected to the copper foil layer which forms a portion of the trace of the head suspension assembly. Thus, it is submitted that Katsumata does not teach or suggest "an insulating component positioned between the conductive element and the heating element such that the conductive element and the heating element are electrically isolated" as recited in claim 28. For at least this reason, Applicant respectfully submitted that claim 28 is in allowable form. Further, it is submitted that dependent claims 29, 31, and 32 are also in allowable form at least based on their relation to claim 28.

For the reasons mentioned above with regard to rejected claims 28, 29, 31, and 32, and based on the indication in the Office Action that claims 1-21, 30, and 33 contain allowable subject matter, it is submitted that all pending claims are in condition for allowance. Reconsideration and allowance are respectfully requested.

The Director is authorized to charge any fee deficiency required by this paper or credit any overpayment to Deposit Account No. 23-1123.

Respectfully submitted,

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